

High Precision Grinding Machine for fast and easy grinding silicon wafer

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Application

The MPS RC is designed for economic grinding silicon wafer up to 8" diameter in semiautomatic mode (Manual loading/unloading; automatic grinding process) at a accuracy of <math><5 \mu\text{m}</math> TTV.

Features

- Diamond wheel;
- Rotary table;
- Vacuum chucks (porous ceramic type);
- Wafer size 2" to 8";
- Automatic fine downfeed;
- Programmable grinding cycles;
- Wet grinding equipment;
- Closed grinding area.

Characteristic

Wafer grinder with vertical grinding spindle and diamond cup grinding wheel.

Combined motor grinding spindle 3.3 kW.

High precision downfeed system with two phase stepping motor and free programmable downfeed speed. Minimal step is 1 μm .

Rotary table speed infinitely variable between 0 and 30 rpm.

Technical Data

Motor	3,3 kW
Spindle speed	2850 rpm
Power connection	4 kW
Accuracy	4 μm
Grinding wheel	
Diamond	200 x 34 x 32 mm
Rotary table	
Dia	320 mm
Speed	0 - 30 rpm
Number of Chucks	
	2" 3" 4" 5" 6" 8"
	18 8 5 3 2 1
Grinding height	300 mm
Fine downfeed	
Range	300 mm
Min. step	1 μm
Weight	350 kg
Area	850 x 700 mm

